

### 1.1 Scope.

This specification covers the detail requirements for a high speed, fast settling monolithic, operational amplifier which is stable at closed-loop gains of 10 or greater.

### 1.2 Part Number.

The complete part number per Table 1 of this specification is as follows:

Device	Part Number
-1	AD840S(Q)/883B
-2	AD840S(E)/883B

### 1.2.3 Case Outline.

See Appendix 1 of General Specification ADI-M-1000: package outline:

#### Package Description

Q-14	14-Pin Cerdip Package
E-20A	20 Contact LCC Package

### 1.3 Absolute Maximum Ratings. ( $T_A = +25^\circ\text{C}$ unless otherwise noted)

Supply Voltage	.....	$\pm 18 \text{ V}$
Internal Power Dissipation <sup>1</sup>	.....	
Q-14	.....	$1.3 \text{ W}$
E-20A	.....	$1.0 \text{ W}$
Input Common-Mode Voltage, Max Safe	.....	$\pm V_S$
Differential Input Voltage	.....	$\pm 6 \text{ V}$
Rated Operating Temperature Range	.....	$-55^\circ\text{C}$ to $+125^\circ\text{C}$
Storage Temperature Range	.....	$-65^\circ\text{C}$ to $+150^\circ\text{C}$
Lead Temperature (Soldering 60 sec)	.....	$+300^\circ\text{C}$

#### NOTE

<sup>1</sup>Maximum internal power dissipation is specified so that  $T_J$  does not exceed  $+175^\circ\text{C}$  at an ambient temperature of  $+25^\circ\text{C}$ . Junction temperatures greater than  $+150^\circ\text{C}$  may cause significant degradation of performance. Therefore, use of a heat sink is recommended if the device is used in high temperature or high output current applications. Derate: Q-14 @ 8.7 mW/ $^\circ\text{C}$ ; E-20A @ 6.7 mW/ $^\circ\text{C}$ .

### 1.5 Thermal Characteristics.

#### Thermal Resistance

Q-14 Package:     $\theta_{JC} = 30^\circ\text{C/W}$   
                        $\theta_{JA} = 110^\circ\text{C/W}$

E-20A Package:     $\theta_{JC} = 35^\circ\text{C/W}$   
                        $\theta_{JA} = 150^\circ\text{C/W}$

# AD840—SPECIFICATIONS

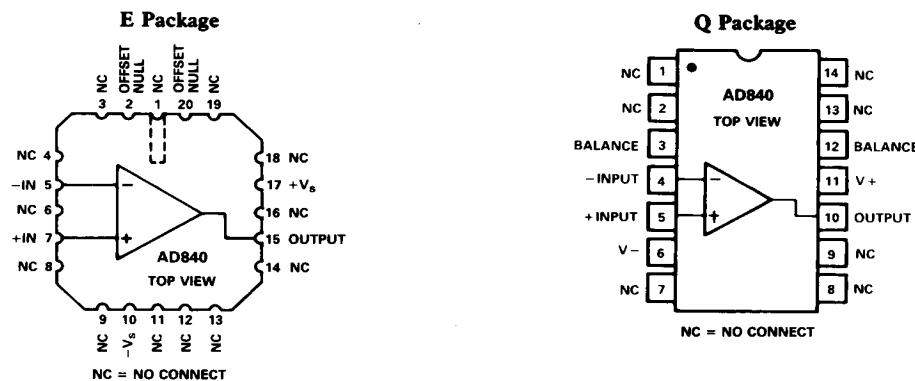
Table 1.

Test	Symbol	Device	Sub Group 1	Sub Group 2, 3	Test Condition <sup>1</sup>	Units
Input Offset Voltage	$V_{OS}$	-1, 2	1	2		$\pm \text{mV}$ max
Input Bias Current	$I_B$	-1, 2	8	12	$V_{CM} = 0 \text{ V}$	$\pm \mu\text{A}$ max
Input Offset Current	$I_{OS}$	-1, 2	0.4	0.6		$\pm \mu\text{A}$ max
Common-Mode Rejection Ratio	CMRR	-1, 2	90	85	$V_{CM} = \pm 10 \text{ V}$	dB min
Open-Loop Gain	$A_{OL}$	-1	100	50	$V_{OUT} = \pm 10 \text{ V}, R_{LOAD} = 1 \text{ k}\Omega$	$\text{V/mV}$ min
		-2	100	30		
		-1	75	50	$V_{OUT} = \pm 10 \text{ V}, R_{LOAD} = 500 \Omega$	$\text{V/mV}$ min
		-2	75	30		
Output Voltage Swing	$V_{OUT}$	-1, 2	10	10	$R_L = 500 \Omega$	$\pm \text{V}$ min
Output Current	$I_{OUT}$	-1, 2	50		$V_{OUT} = 0 \text{ V}$	$\pm \text{mA}$ min
Power Supply Rejection Ratio	PSRR	-1, 2	90	80	$V_S = \pm 5 \text{ V}$ to $\pm 18 \text{ V}$	dB min
Power Supply Current	$I_Q$	-1, 2	14	18	$V_{OUT} = 0 \text{ V}$	$\text{mA}$ max

NOTE

<sup>1</sup> $V_S = \pm 15 \text{ V}$ , unless otherwise specified.

### 3.2.1 Functional Block Diagram and Terminal Assignments.



### 3.2.4 Microcircuit Technology Group.

This microcircuit is covered by technology group (85).

### 4.2.1 Life Test/Burn-in Circuit.

Steady state life test is per MIL-STD-883 Method 1005. Burn-in is per MIL-STD-883 Method 1015 test condition (B).

#### Q Package Pinout

